SUSS MICROTEC INVESTOR PRESENTATION

February 2014

DISCLAIMER

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

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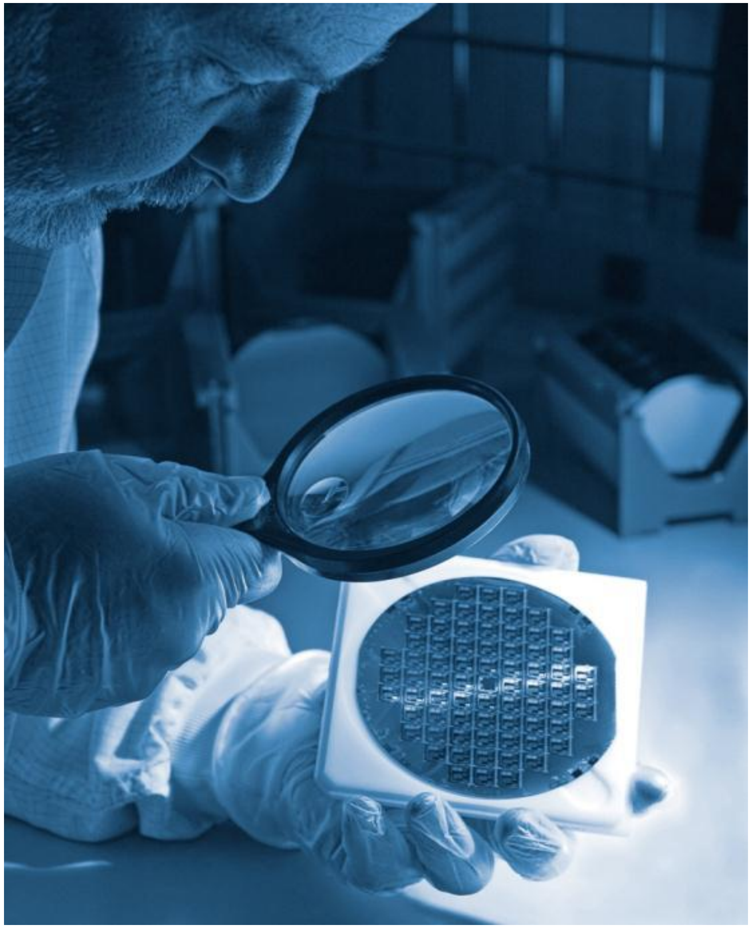
SUSS MICROTEC AT A GLANCE

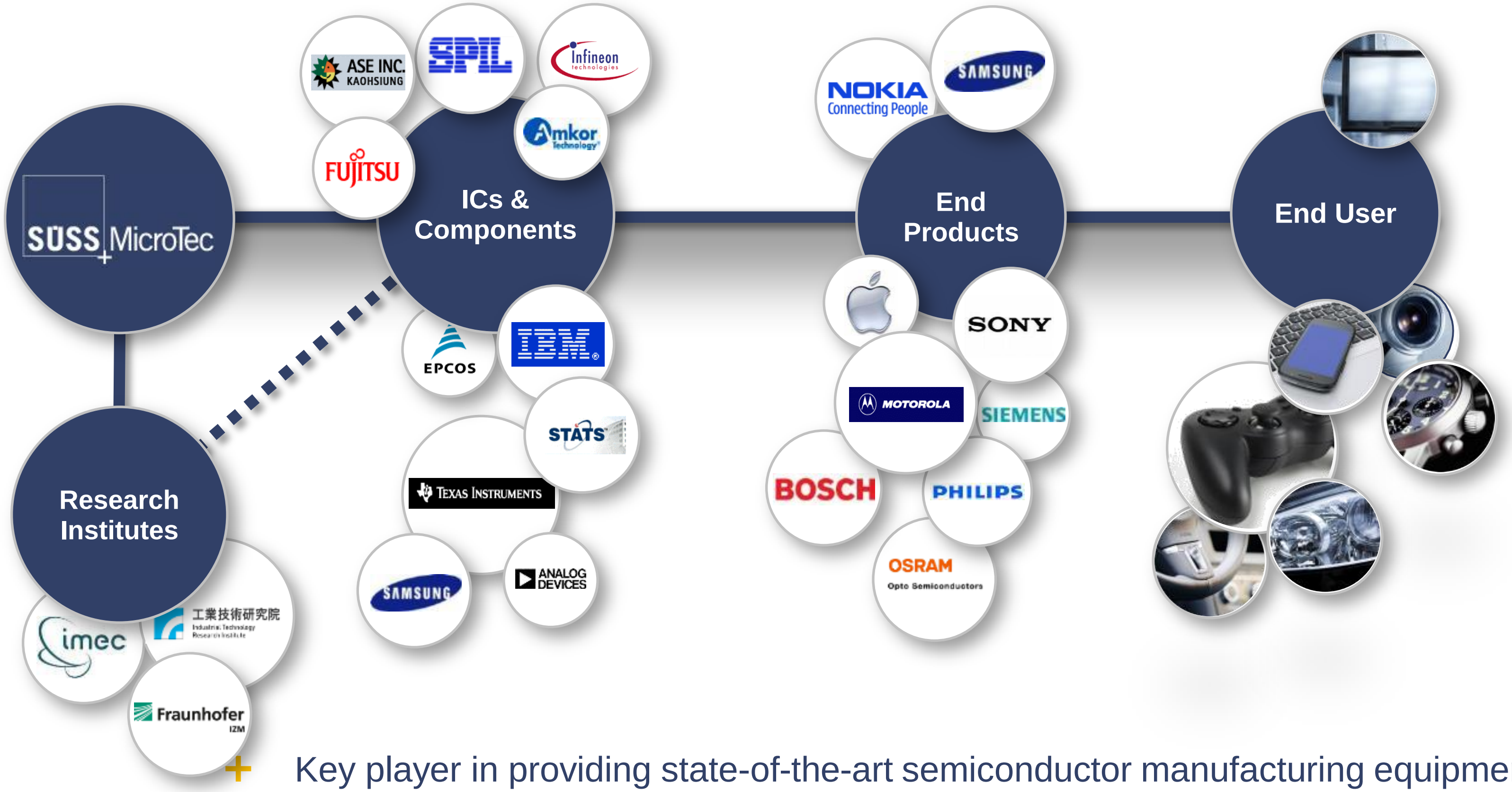
- SUSS MicroTec: A global leader in semiconductor equipment
- Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- We are focused on high growth market segments: Semiconductors, MEMS, LEDs



- Key Data:
  - Stock Exchange Symbol: SMHN
  - Share price*: 7.24 €
  - Market Cap*: 138 € million
  - Net Cash, December 31, 2013: 35.7 € million

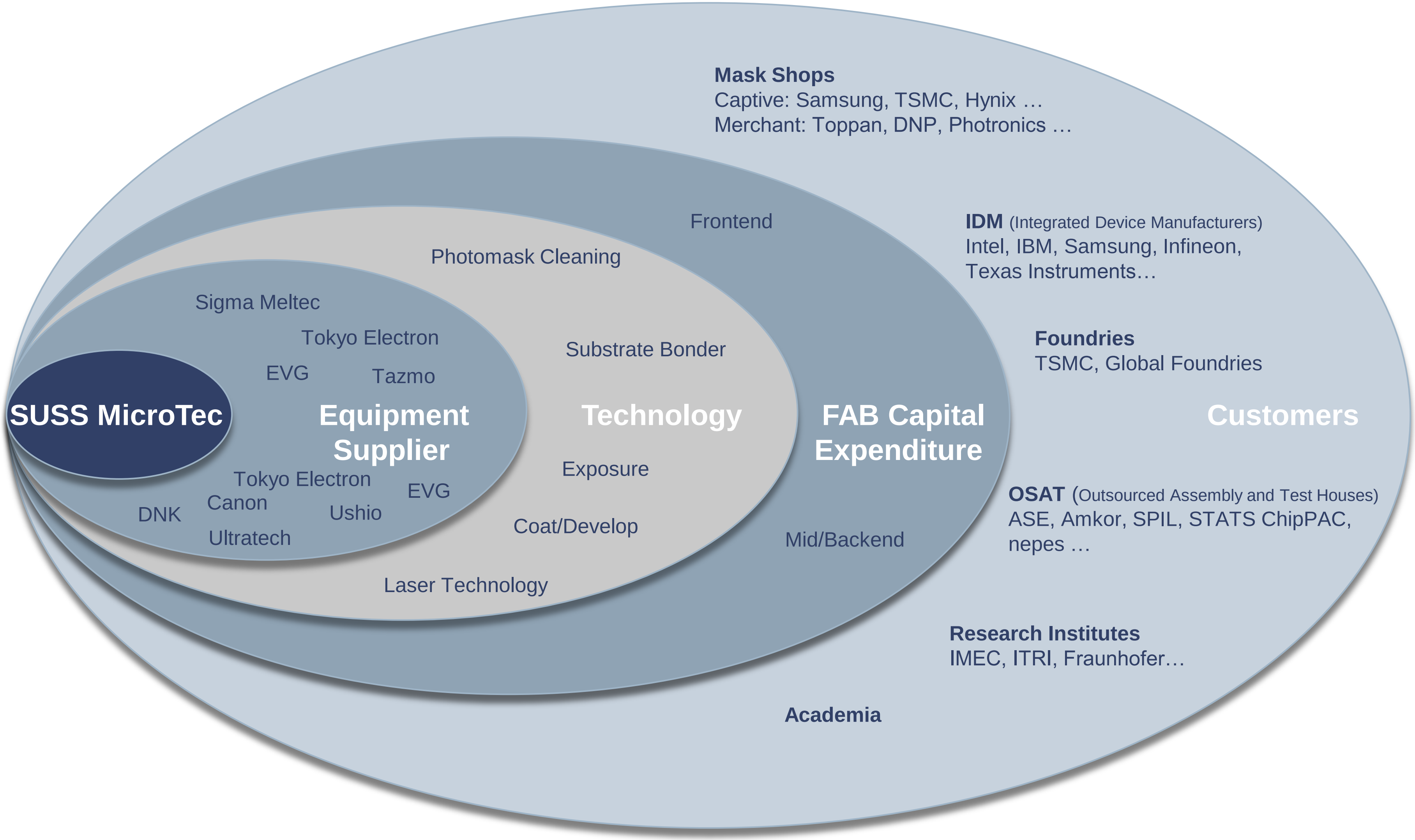
* January 31, 2014

SUSS MICROTEC IN THE VALUE CHAIN



- Key player in providing state-of-the-art semiconductor manufacturing equipment
- Development of highly innovative process solutions with industry and R&D partners
- Components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec’s equipment

THE SEMICONDUCTOR MARKET



SUSS MicroTec

Equipment Supplier

Sigma Meltec

Tokyo Electron

EVG

Tazmo

Tokyo Electron

Canon

EVG

DNK

Ushio

Ultratech

Technology

Photomask Cleaning

Substrate Bonder

Exposure

Coat/Develop

Laser Technology

FAB Capital Expenditure

Frontend

Mid/Backend

Customers

Mask Shops
Captive: Samsung, TSMC, Hynix …
Merchant: Toppan, DNP, Photronics …

IDM (Integrated Device Manufacturers)
Intel, IBM, Samsung, Infineon,
Texas Instruments…

Foundries
TSMC, Global Foundries

OSAT (Outsourced Assembly and Test Houses)
ASE, Amkor, SPIL, STATS ChipPAC,
nepes …

Research Institutes
IMEC, ITRI, Fraunhofer…

Academia

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA

🟦 Sunnyvale, US
▨ Corona, US

EUROPE

■ ▨ Garching, DE
▨ Sternenfels, DE
▨ Hâuterive, CH
🟦 Lyon, FR
🟦 Coventry, UK

ASIA

🟦 Yokohama, JP
🟦 Hwaseong City, KR
Singapore, SG 🟦
🟦 Shanghai, CN
🟦 Hsin Chu, TW

■ Headquarters
▨ Production
🟦 Sales

MAIN PRODUCTION SITES

Germany

Garching

- SUSS MicroTec HQ
- Development/production:
  - **Mask Aligner**
  - **Bond Aligner**
- Core competencies:
  - **Exposure** (proximity exposure)
  - **Alignment**

Sternenfels

- Development/production :
  - **Bonder**
  - **Coater and Developer**
  - **Photomask Equipment**
- Core competencies:
  - **Wet processing**
  - **Wafer bonding**

USA

Corona

- Development/production:
  - **Stepper/Scanner**
  - **Laser Processing**
- Core competencies:
  - **Exposure** (UV projection lithography)
  - **Laser Ablation**

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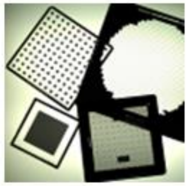
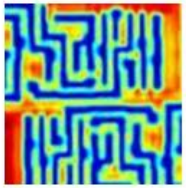
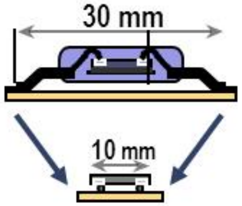
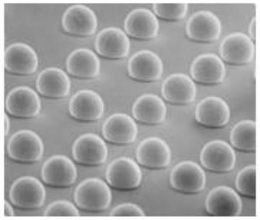
KEY MARKETS

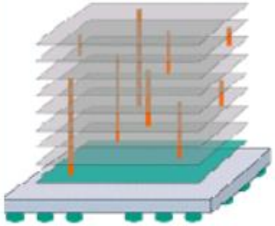
Semiconductors			Sensors	Lighting
Mask Manufacturing Photomask Cleaning	**Advanced Packaging** Micro-Bumping	**3D Integration/Stacking**	**MEMS** Computing, Automotive, Medical Applications …	**LED** General Lighting, HB and UHB LED

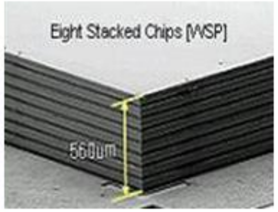


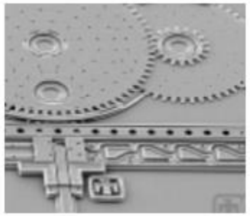


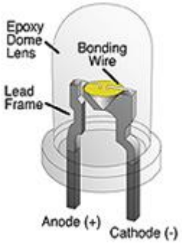












SEGMENTS, PRODUCTS AND MARKETS

Segments	Photomask Equipment	Lithography			Substrate Bonder
Products	 MaskTrack Pro	 Exposure Systems		 Coater/Developer	 Wafer Bonder
	Frontend	Mid- and Backend			
Process Steps	Photomask Cleaning	Stepper, Scanner (UV projection) Laser Ablation	Mask Aligner (proximity exposure) Nano Imprinting	Coating Developing	Bond Alignment Permanent Bonding Temporary Bonding
Key figures 9M 2013	Sales: 15.7 € million EBIT: 0.9 € million	Sales: 64.9 € million EBIT: 2.6 € million			Sales: 9.8 € million EBIT: -16.0 € million

Markets

- Mask Manufacturing
- Advanced Packaging
- 3D Integration
- MEMS
- LED

RESTRUCTURING OF PERMANENT BONDING

+ **Reevaluated the business situation in permanent bonding**
  - ongoing losses with one product

+ **Discontinued production of loss making cluster systems**

+ **Cumulative expenses for the restructuring of permanent bonding in 2013 amount to approximately € 13.2 million**

+ **Losses of the Substrate Bonding Division will be reduced significantly**

+ **The successful manual permanent bonding systems are not affected**

+ **Strong focus on temporary bonding applications for 3D TSV production**

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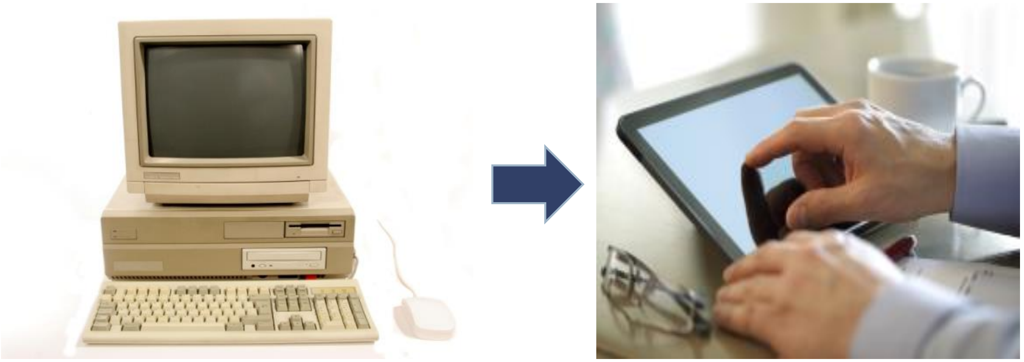
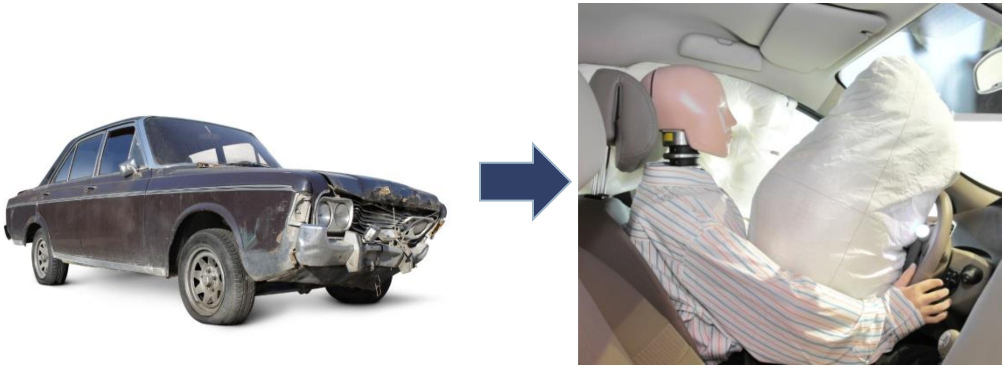
TECHNOLOGY EVOLUTION

~1985...today



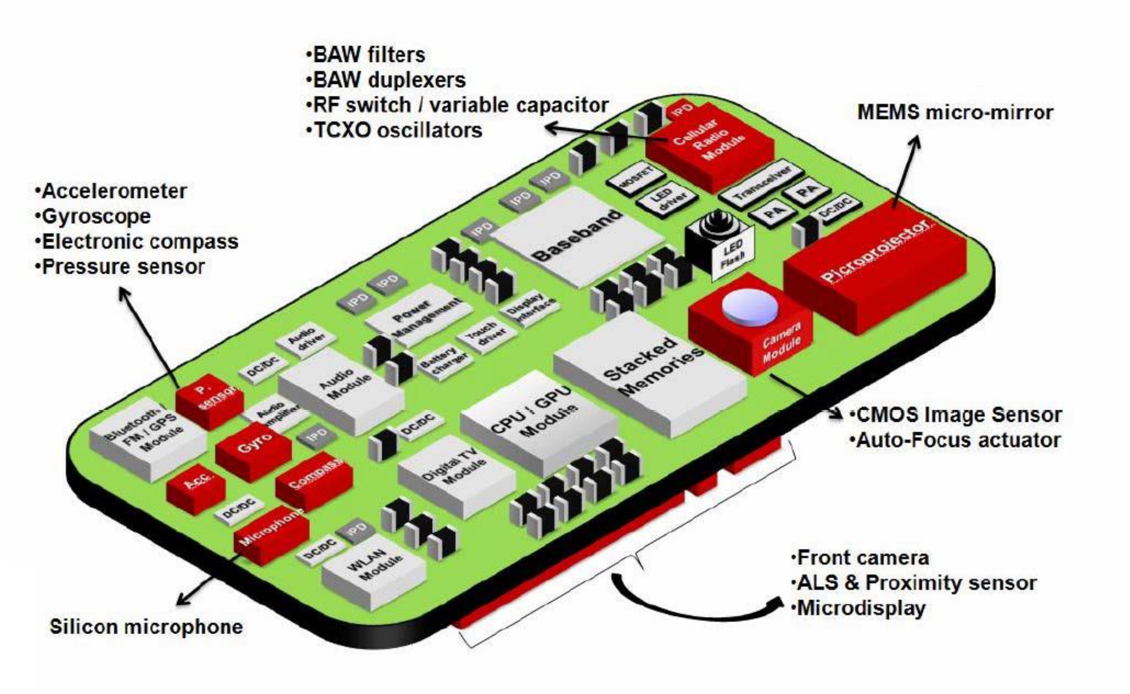
~1987...today

~1910...today



~1950...today

GROWTH DRIVER SMARTPHONES AND TABLETS



- BAW filters
- BAW duplexers
- RF switch / variable capacitor
- TCXO oscillators

MEMS micro-mirror

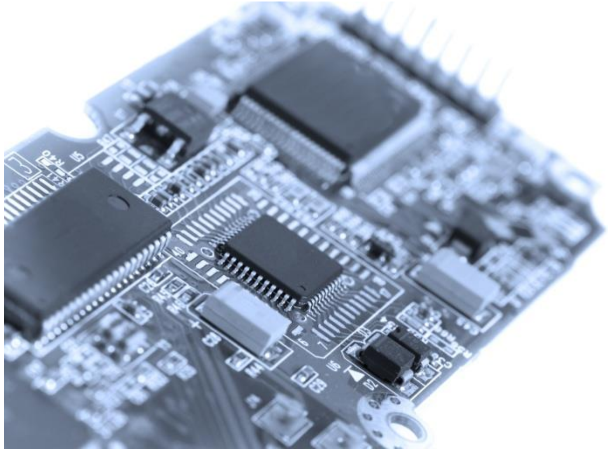
- Accelerometer
- Gyroscope
- Electronic compass
- Pressure sensor

- CMOS Image Sensor
- Auto-Focus actuator

- Front camera
- ALS & Proximity sensor
- Microdisplay

Silicon microphone

Source: Yole Developpement



MICROCHIPS, MEMS UND LED: BUILDING BLOCKS FOR TECHNOLOGICAL PRODUCT ADVANCEMENT

Digital Lifestyle

- The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media
- Mobile devices like smartphones and tablet PCs provide this capability at affordable cost
- New device generations offer higher functionality

E-Mobility

- Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios
- EVs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices but also high performance ICs

Energy Efficiency

- Increase environmental awareness and rising energy prices and fuel the demand for energy efficient solutions in electricity usage i.e. lighting
- Energy efficiency in industrial production
- Smart energy management in household applications safes energy

EXPECTED MARKET DEVELOPMENTS

With its strong position in the fast growing target markets 3D Integration / Advanced Packaging, LED and MEMS, SUSS MicroTec can benefit from the market developments:

Advanced Packaging	Wafer level packaging and flip chip is expected to remain more robust than the overall market, primarily driven by mobile devices like smart phones and tablets
3D Integration (TSV)	Transition to production volume in the years to come
Compound Semiconductors	LED, MEMS, RF, Optoelectronics, III-V Power are expected to remain robust based on smartphone and tablet growth and will drive further demand for advanced packaging solutions

Segment growth 2011 - 2016E CAGR ~ 15% (Gartner and industry estimates)

SCALING TECHNOLOGIES FROM 2D TO 3D

2D Packaging

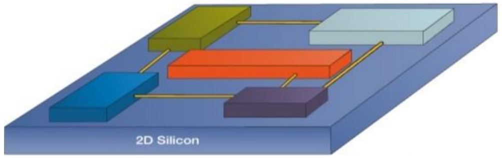
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore‘s Law
- New technologies like EUV and multiple pattering allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

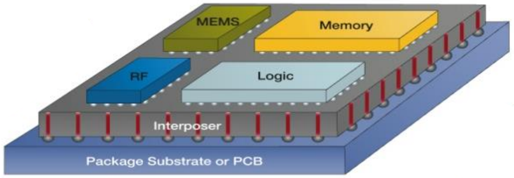
2.5D Packaging

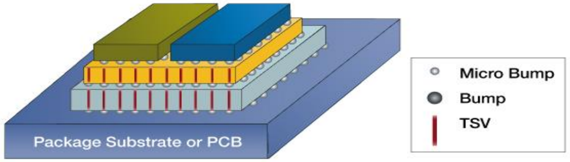
- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore‘s Law

3D Integration (TSV)

- The extension beyond the conventional shrink roadmap is called "More than Moore“
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption







SUSS MicroTec‘s equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")

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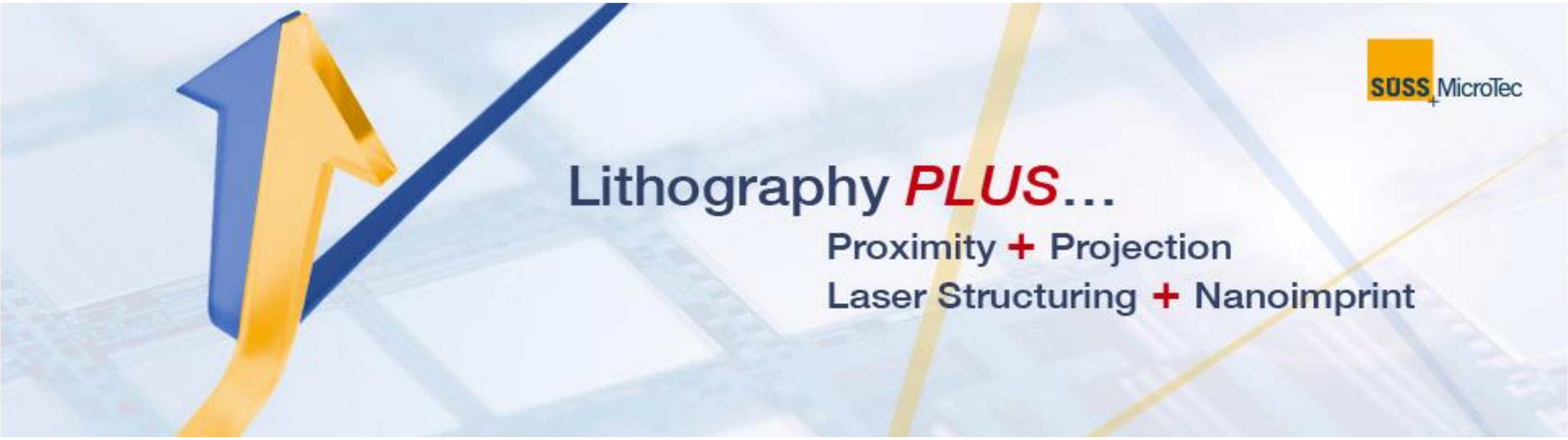
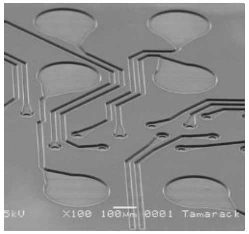
LITHOGRAPHY COMPETENCY

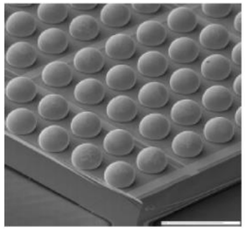
- Increasing chip performance requires the adoption of innovative lithography technologies in the semiconductor backend
- **Not one single exposure technology fits all needs at the same time**
- The newly acquired Stepper/Scanner products supplement our Mask Aligner product line and enlarges our technology portfolio by the key competencies UV-projection lithography and laser ablation
- SUSS MicroOptics S.A. adds key know how for critical lithography performance improvements



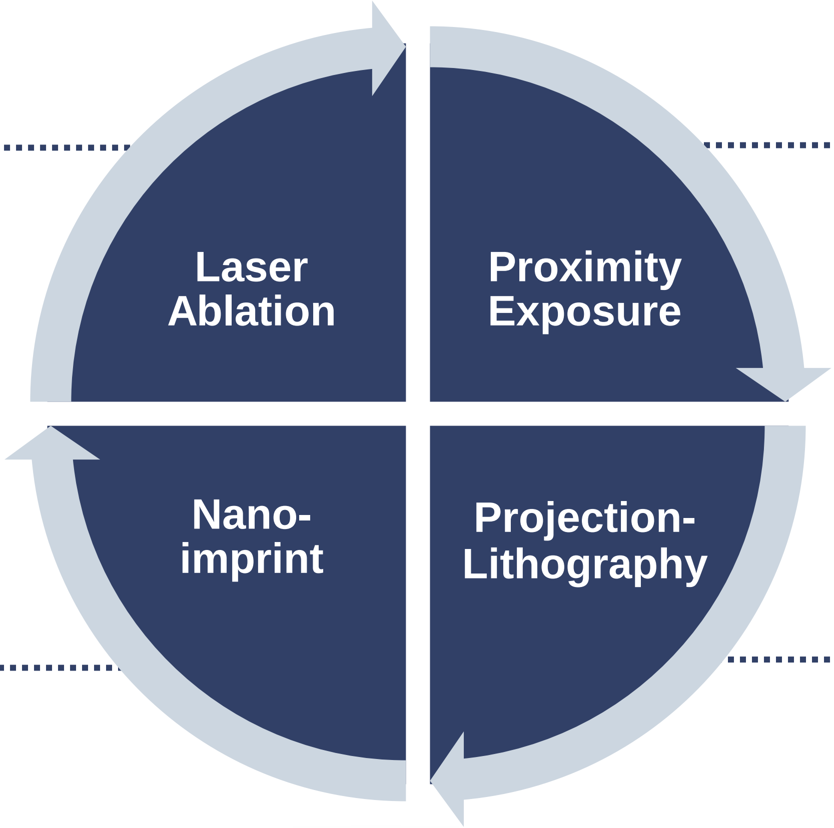
EXPOSURE SOLUTIONS



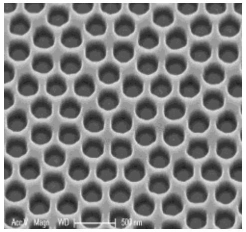
WLCSP:
Fanout WLP



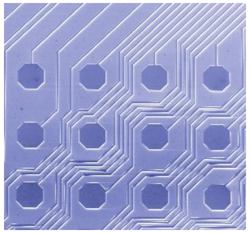
Flip Chip:
Solder Bumping



LED:
Photonic Crystals



WLCSP:
Fine pitch RDL



+ **Only SUSS MicroTec offers complete exposure solutions for the mid-/back-end**

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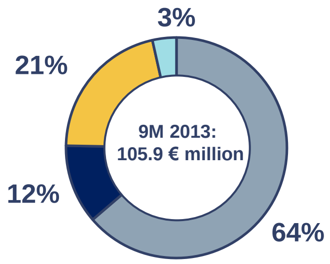
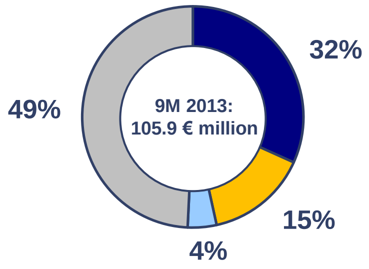
ORDER ENTRY AND SALES BY SEGMENT AND REGION 9M 2013

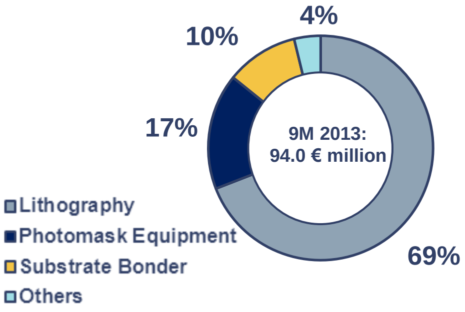
Order Entry by Segment



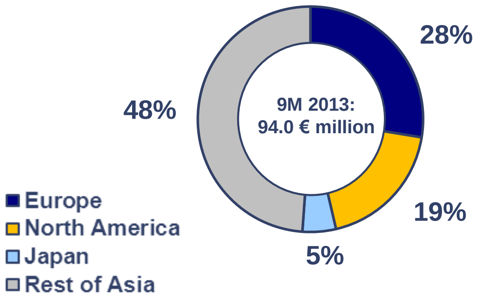
Order Entry by Region



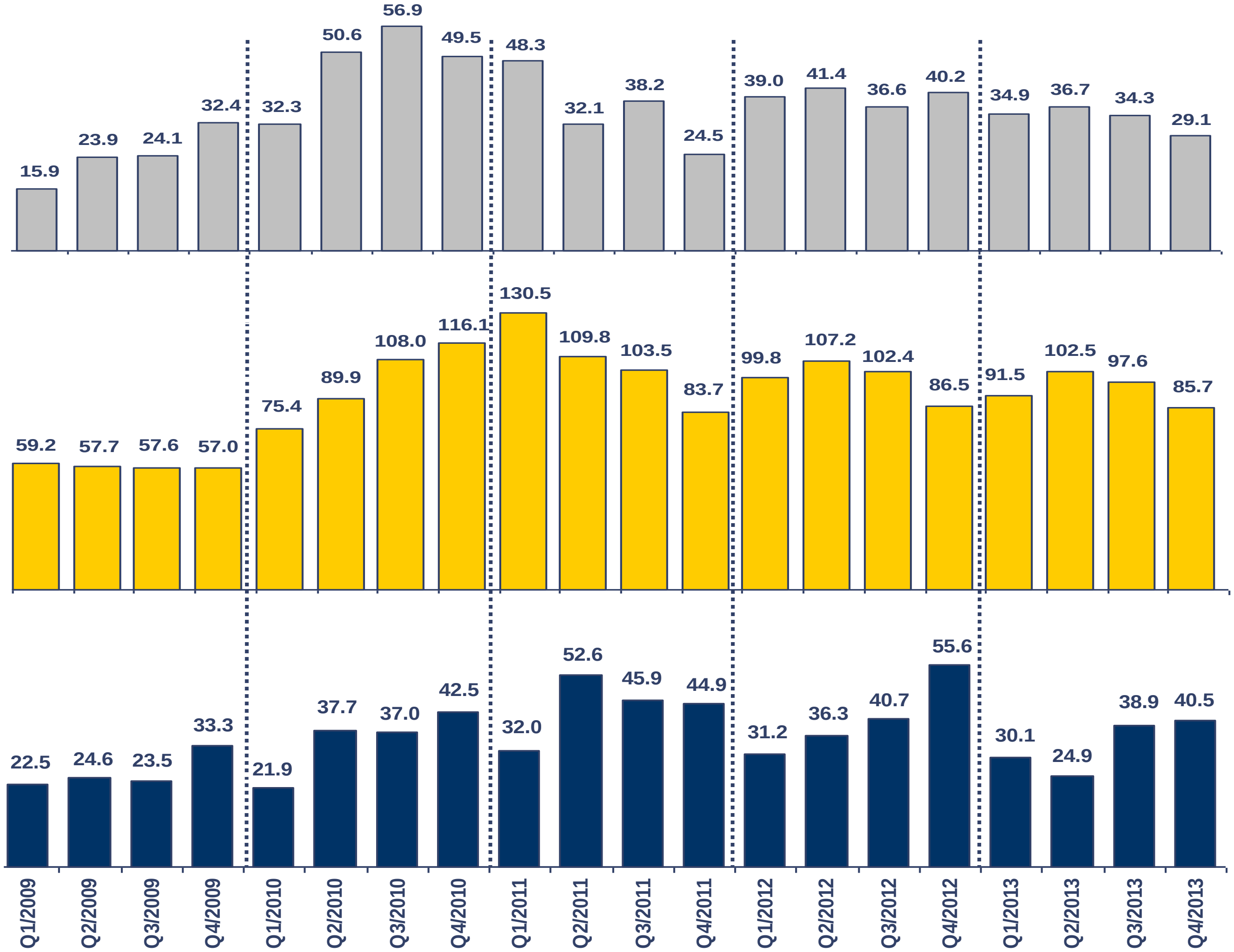
Sales by Segment



Sales by Region



LONG TERM BUSINESS DEVELOPMENT

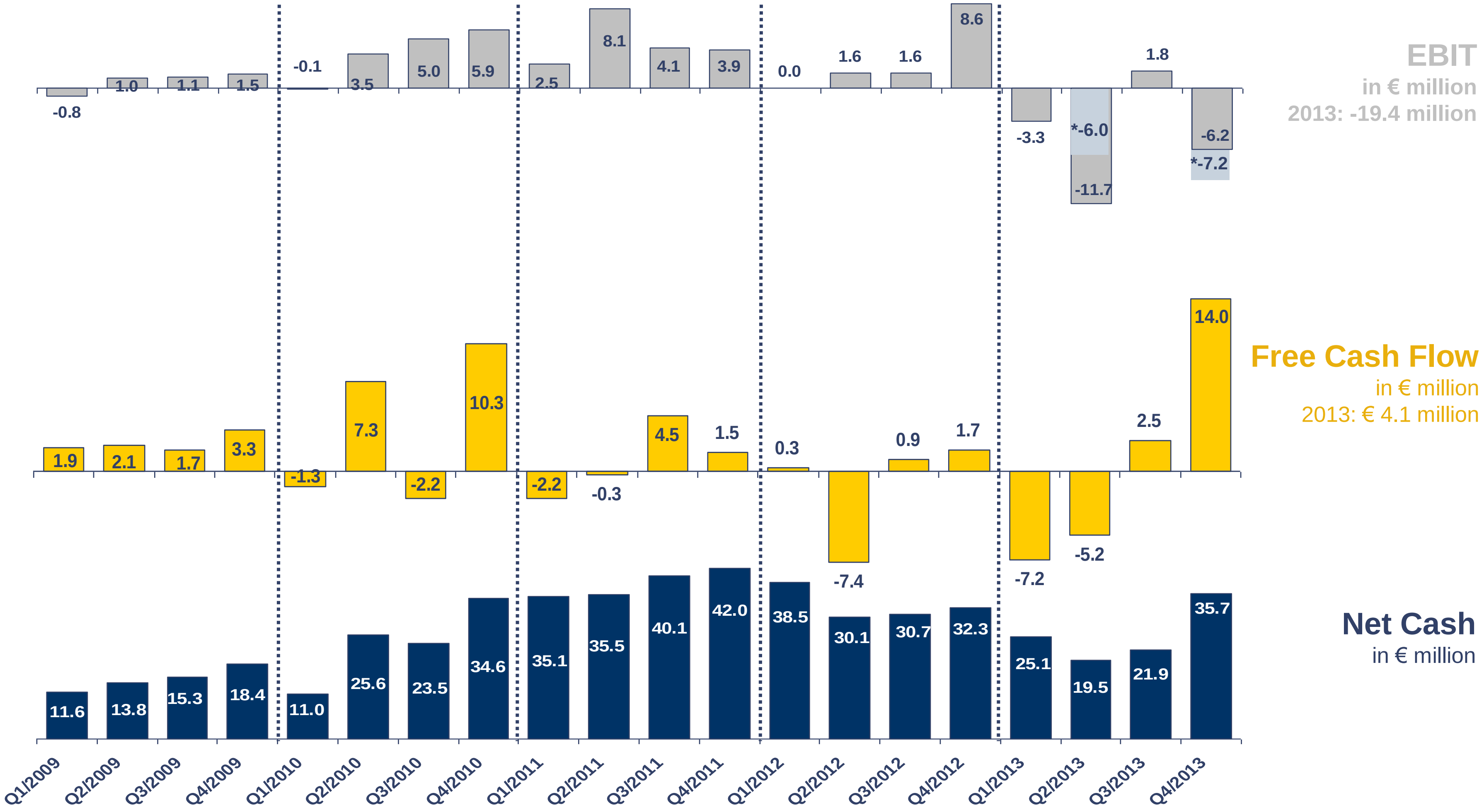


Order Entry
in € million
2013: € 135 million

Order Backlog
in € million

Sales
in € million
2013: € 135 million

EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effects from restructuring of the product line permanent bonding

KEY FINANCIALS (PRELIMINARY NUMBERS)

in € million	2013	2012	YoY in %
Revenue	**134.5**	**163.8**	**-17.9%**
Order Intake	**135.0**	**157.2**	**-14.1%**
Order Backlog 12/31	**85.7**	**86.5**	**-0.9%**
EBIT	**-19.4**	**11.7**	**--**
EBIT in % of Sales	*-14.4%*	*7.1%*	*-21.5%pt.*
EBIT (adjusted)	**-6.2**	**10.3**	**--**
EBIT (adjusted) in % of Sales	*-4.6%*	*6.3%*	*--*
Net Cash*	**35.7**	**32.3**	**+10.5%**
Free Cash Flow**	**4.1**	**-4.5**	**--**

* incl. stock of interest-bearing securities

**before consideration of purchased interest-bearing securities , the acquisition of Tamarack and the gain out of the sale from the Test Business

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SUMMARY AND OUTLOOK

2013:
- Milestone achievement in temporary bonding
- Restructuring of product line Permanent Bonding expanded
- Further integration of SUSS MicroTec Photonic Systems

Fundamental growth in target markets

Strong competitive positioning: first or second in the target markets

Leading equipment company in the semiconductor backend, enabling “Moore’s Law”as well as “More than Moore”

Outlook

FY 2014:
- Sales of 135 - 145 € million
- EBIT: - 5 to 0 € million

Q1 2014:
- Order Entry of 25 - 35 € million

SÜSS MicroTec AG
Schleissheimer Str. 90
85748 Garching

www.SUSS.com

INVESTOR RELATIONS INFORMATION

Contact

Franka Schielke

Tel.: +49 (0) 89-32007- 161
Fax.: +49 (0) 89-32007- 451
Email: franka.schielke@suss.com

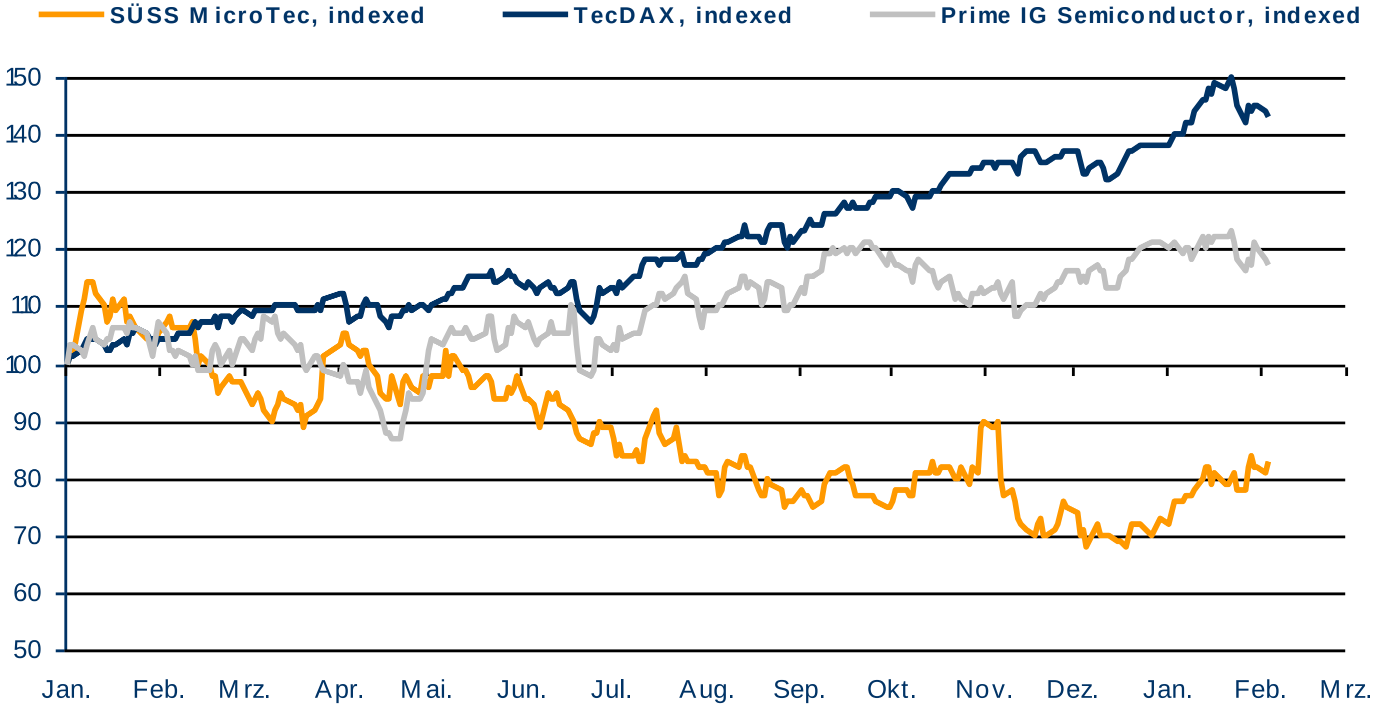
SÜSS MicroTec AG
Schleissheimer Strasse 90
85748 Garching (Munich)
Germany
www.suss.com

Financial Calendar 2014

Annual Report 2013	28 Mar
Quarterly Report 2014	8 May
Berenberg Investment Conference Paris	22 May
Deutsche Bank Investment Conference, Berlin	12 - 13 Jun
Shareholders' Meeting, Haus der Bayerischen Wirtschaft, Munich	17 Jun
Interim Report 2014	7 Aug
Nine-month Report 2014	6 Nov
German Equity Forum 2014, Frankfurt am Main	24 - 26 Nov

STOCK PERFORMANCE: JANUARY 2013 – FEBRUARY 2014

(Price of the SUSS MicroTec Share at January 2, 2013: 8.85 €)



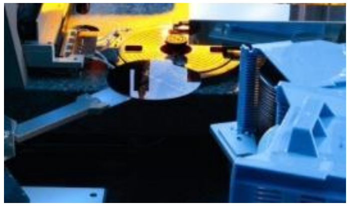
Average daily trading volume January 2013 – February 2014: ~ 104,000

SUSS MICROTEC PRODUCT PORTFOLIO

Photomask Equipment

Coater/Developer

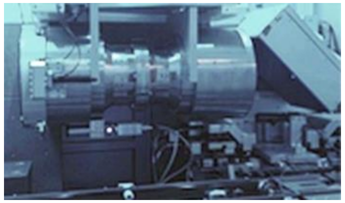
Wafer Bonders



Alignment Verification Systems

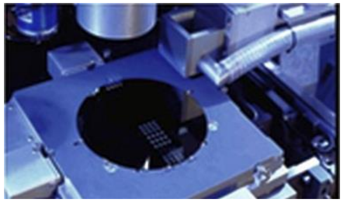
Mask Aligners

Imprinting Systems



UV-Projection

Stepper / Scanner



Excimer Laser

Systems